#### **Description**

The 1N65G uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 600V I<sub>D</sub> =1A

 $R_{DS(ON)}$  < 12 $\Omega$  @  $V_{GS}$ =10V

## **Application**

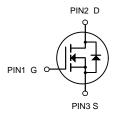
Battery protection

Load switch

Uninterruptible power supply







N-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
1N65G	SOT-223(SOT-223-4)	1N65 XXXX	2500

### Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter Rating		Units	
Vps	Drain-Source Voltage	ource Voltage 600		
Vgs	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	1	Α	
Іом	Pulsed Drain Current <sup>2</sup>	4.8	Α	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	
Reja	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	62.5	°C/W	



### **Electerical Characteristics** ( T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	600			V
△BVDSS/△TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.057		V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =0.6A		9.5	12	Ω
V <sub>GS</sub> (th)	Gate Threshold Voltage	N N 1 050 A	2		4	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.68		mV/°C
		V <sub>DS</sub> =650V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =650V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
Igss	Gate-Source Leakage Current	$V_{GS}=\pm30V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =0.5A		35		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			4		
Qgs	Gate-Source Charge	V <sub>DS</sub> =520V , V <sub>GS</sub> =10V , I <sub>D</sub> =1A		0.9		nC
Q <sub>gd</sub>	Gate-Drain Charge			2.5		
Td(on)	Turn-On Delay Time			4		
Tr	Rise Time	V <sub>DD</sub> =325V , V <sub>GS</sub> =10V , —R <sub>G</sub> =50 Ω ,		24		
Td(off)	Turn-Off Delay Time	I <sub>D</sub> =1A		6		ns
T <sub>f</sub>	Fall Time			24		
Ciss	Input Capacitance			119		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		19		pF
Crss	Reverse Transfer Capacitance			2		
Is	Continuous Source Current <sup>1,5</sup>				1	Α
Іѕм	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			4.8	Α
Vsp	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	IF=15A , dI/dt=100A/μs ,		160		nS
Qrr	Reverse Recovery Charge	IF=15A , di/dl=100A/μs , T_=25°C		0.3		nC

#### Note:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqq 300 us$  , duty cycle  $\leqq 2\%$
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
- 4.The power dissipation is limited by 150°C junction temperature 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation

# **Typical Characteristics**

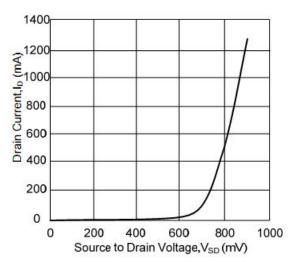
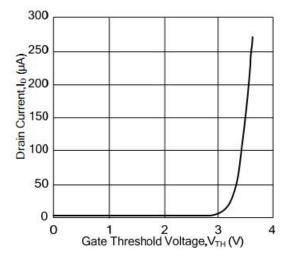


Fig1.Drain Current vs. Source to Drain Voltage



Drain Current vs. Fig3.Gate Threshold Voltage

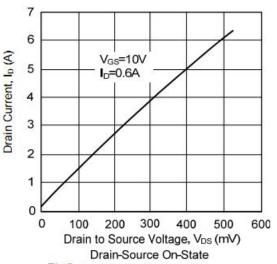
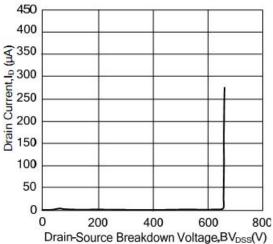


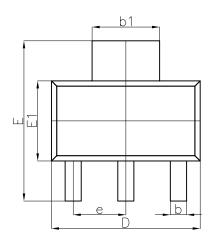
Fig2. Resistance Characteristics

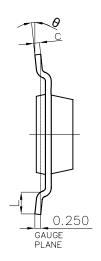


Drain Current vs. Fig4.Drain-Source Breakdown Voltage



# SOT-223 SOT-223-Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α		1.800		0.071	
A1	0.020	0.100	0.001	0.004	
A2	1.500	1.700	0.059	0.067	
b	0.660	0.840	0.026	0.033	
b1	2.900	3.100	0.114	0.122	
С	0.230	0.350	0.009	0.014	
D	6.300	6.700	0.248	0.264	
E	6.700	7.300	0.264	0.287	
E1	3.300	3.700	0.130	0.146	
е	2.300(BSC)		0.091(BSC)		
L	0.750		0.030		
θ	0°	10°	0°	10°	



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